

ABSTRACT

A semiconductor chip having contacts on a front surface is provided with pads and traces on the rear surface. These pads and traces desirably are not electrically connected to internal components within the chip. In a stacked assembly, a chip overlies the rear surface of the first-mentioned chip and is connected to the pads. The traces are connected to a substrate such as a circuit board, as by wire-bonding before applying the second chip, so that the second chip is electrically connected to the substrate through the pads and traces.

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